

# Non-Volatile Flash Memory Module SafeGuard Data Recorder

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# Why Non-Volatile Mass Memories?

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- **Benefits:**
  - Non-Volatile
    - ⇒ Data immune against Power Breakdowns
    - ⇒ Power Savings
    - ⇒ SEFI / SEL recovery without data loss in contrast to SRAMs / DRAMs
  - Densest Mem. Techn. available
    - ⇒ High Capacity (NAND)
- **This can be exploited to enhance and to optimize Missions with strong requirements with respect to**
  - Autonomy (Deep Space)
  - Complex Mission Modes (Operational Scenarios)
  - Long term or frequent Power Off Phases during the Mission
  - Low Power Requirements (Smart S/C, Outer Solar Systems)
  - Storage of Mission Critical Data, Emergency Commands, SW Patches
  - Sparse download / upload Capabilities
  - etc.

# SafeGuard Data Recorder

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- **Main Design Drivers:**

- Non-Volatility combined with Robustness of semiconductor Storage Devices
- Excellent Data Integrity after Long Term Storage

- **Tentative Technical Features:**

- Pure NAND Flash Memory Core
- Safe with Respect to Power-Outages
- Multiple Orthogonal RS Error Correction grants high Data Integrity in harsh Radiation Environment
- File Management including Management of Circular Buffers
- Interfaces compliant to HICDS
- Capacity: 4 GByte per Module
- Write Performance: 6 MByte/s
- Read Performance: 25 MByte/s
- Data Integrity: < 1 Error / 1 MByte / 10 years without refresh

# SGDR Non-Volatile Storage Technology

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- **Preferred Technology: Flash EEPROM NAND Type**
  - (+) Widely used commercial Technology
  - (+) Intrinsic Non-Volatility by Technology
  - (+) Large Storage Density (up to 2 Gbit per Device)
  - (+) Heavy Ion SEE Tests of 1 Gbit Devices delivered encouraging Results
  - (+) Data Retention up to 10 Years, extendable by Refresh
  - (+) Performance tailored to a wide Spectrum of Applications
  
  - (-) Moderate Data Input Rate 1 MByte/s/dev
  - (-) Endurance limited to approximately  $10^6$  Write Cycles, can be extended by Wear Levelling

# Failure Effects and Countermeasures

Error / Failure Modes:	Corrective Measures:
<u>Distributed</u> single Byte <u>Errors</u> in retrieved Page Data	Flow Through Orthogonal RS Error Correction (uninterrupted Data Flow)
<u>Bulk Errors</u> in retrieved Page Data, Write Verification Errors, Block Errors, SEFIs, Device Failures	Access Repetition, If Error persists: Device Interrupt and / or Power Cycling, If Error still persists: Move corrected Page to another uncontaminated Page, Write to another Page, etc.
Endurance	Wear Levelling
Data Retention	Scrubbing Move corrected Page / Block
Latch Up	Current Monitoring Power Cycling

**All Errors / Failure Modes can be detected and coped by dedicated Countermeasures!  
To minimize SEFIs the Flash Devices are powered only during Access Periods.**

## Device Level: Open Issues

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- **Final Evaluation of the Heavy Ion SEE Test Results nearly completed.**
- **Preliminary Summary of the SEE Test Results available in SGDR Phase 1 Final Report (SGDR-RP-7001)**
- **Open Issues resulting from Phase 1 SEE Tests:**
  - Power cycling after erase is an effective countermeasure against (all?) persistent device failures and SEFIs. But this statement is based on only a few devices tested up to now. Therefore additional attention will be given to this topic in the next tests with new devices.
  - Discrepancy between the storage mode cross section values gained by low penetration beam tests and by high penetration beam tests. A repetition of the low penetration beam tests is regarded to be the next reasonable step for disclosing this discrepancy.
  - Data retention and endurance behaviour of Flash devices under radiation could not be investigated up to now.

# SGDR Phase 1 Activities

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- **Performed Tasks**
  - Storage Technology Evaluation
  - Heavy Ion SEE Tests
  - System Analysis
  - Data Integrity Analysis
  - Elaboration of Provisions to enhance Data Integrity
  - Requirement Specification
- **Results are summarized in SGDR Phase 1 Final Report (SGDR-RP-7001)**

# SGDR Phase 2 Activities

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- **Next Tasks**

- Phase 2 Radiation Tests
  - Open Issues from SEE Phase 1 Tests
  - Proton Tests
  - TID Tests
- Architectural SGDR Design
- Operations and Functions
- Detailed Module Design
- MAIT of EM Module

- **Goal**

- SGDR EM Memory Module available End of 2006